

(To be filled in by TÜV Rheinland)

Constructional Data Form

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License holder: **Tyco Electronics Japan G.K.**
 3-5-8 Hisamoto, Takatsu-ku, Kawasaki-shi, Kanagawa 213-8535 Japan

Factory: **TE Connectivity Connectors(Suzhou) Co., Ltd.**
 (Full address) No.33 Chunyao Road, Caohu Subdistrict, Suzhou Xiangcheng Economic Development Zone, Suzhou, Jiangsu 215000, P.R. China.

Tyco Electronics Japan G.K. Kakegawa Distribution Center
 102 Shoubugaike, Kakegawa-Shi, Shizuoka-ken, 436-0040 Japan

Type or Model Number: Dynamic D-5200 Series Connector
 Kind of device: Electrical Connector

Specifications	
Type designation	Dynamic D-5200 Series Connector
Contact material	Copper Alloy with silver plating
Number of poles	4 (See Table-1)
Rated voltage	Overvoltage category II & Pollution degree 2: 630 V AC/DC Overvoltage category III & Pollution degree 2: 600 V AC/DC Overvoltage category III & Pollution degree 3: 400 V AC/DC
Rated current	57A MAX (Reference derating curve, see Figure 1)
Mechanical endurance	50
Classification	<input type="checkbox"/> CBC <input checked="" type="checkbox"/> Non CBC <input type="checkbox"/> other:
Number of bendings (non-rewirable terminals only)	N/A
Upper limit temperature	105 °C
Lower limit temperature	-55 °C

IP Degree Conditions		
Type of connector	Receptacle	Tab Header
IP code	IP-10 <input checked="" type="checkbox"/> mated <input type="checkbox"/> unmated	IP-00 <input checked="" type="checkbox"/> mated <input type="checkbox"/> unmated
Backshell	N/A	N/A
Cable clamp	N/A	N/A
Cable range	N/A	N/A
Fastening torque	N/A	N/A

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KAWASAKI

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Insulation Coordination	
Overvoltage category	II and III
Pollution degree	2, 3
Test voltages	Contact – contact : 4800 Vp Shell – contact : N/A
Minimum creepage distances	Contact – contact : 6.5 mm Shell – contact : N/A
Minimum clearance distances	Contact – contact : 6.5 mm Shell – contact : N/A
Insulation system (IEC 60664-1)	Contact – contact : <input checked="" type="checkbox"/> basic <input type="checkbox"/> reinforced <input type="checkbox"/> NA Shell – contact : <input type="checkbox"/> basic <input type="checkbox"/> reinforced <input checked="" type="checkbox"/> NA

Specifications (terminals)	
Type of terminals	<input type="checkbox"/> WRAPPED CONNECTIONS <input checked="" type="checkbox"/> SOLDER TERMINALS <input type="checkbox"/> CLIP CONNECTIONS <input checked="" type="checkbox"/> CRIMPED CONNECTIONS <input type="checkbox"/> INSULATION DISPLACEMENT CONNECTIONS <input type="checkbox"/> PRESS-IN CONNECTIONS <input type="checkbox"/> SCREWLESS TERMINALS <input type="checkbox"/> SCREW TERMINALS <input type="checkbox"/> FLAT, QUICK CONNECT TERMINATIONS <input type="checkbox"/> other:
Terminal designation	See Table-2.
Material / Plating Material	Copper alloy with silver plating
Spec. Tightening torque	N/A
Rated cross section of conductor	AWG# 8 to 20
Type of conductor	Flexible (Stranded copper wire)
Required preparation of the conductor	N/A
Max. Stripping length	7.5 mm
Max. Number of conductors per terminal	1

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TYPE NOMENCLATURE:

Connector (receptacle and tab header): Table-1

Poles	Receptacle	TAB Header	
		Horizontal type	Vertical type
4	□-917807-2	□-1318983-6 □-2134124-6	□-1981458-6

Note; The prefixes 0 to 6 denote different keying type.

Terminal designation: Table-2

Wire Range AWG#	Receptacle Component	
	Strip Form*	Loose Form*
20-16	1318985-6	1318986-6
16-14	179955-6	316040-6
12-10	179956-6	316041-6
8	1318696-6	1318697-6

* Different packaging form

Derating curve (D5200alpha 4P Ag plating, AWG#8, derating factor: 0.8)

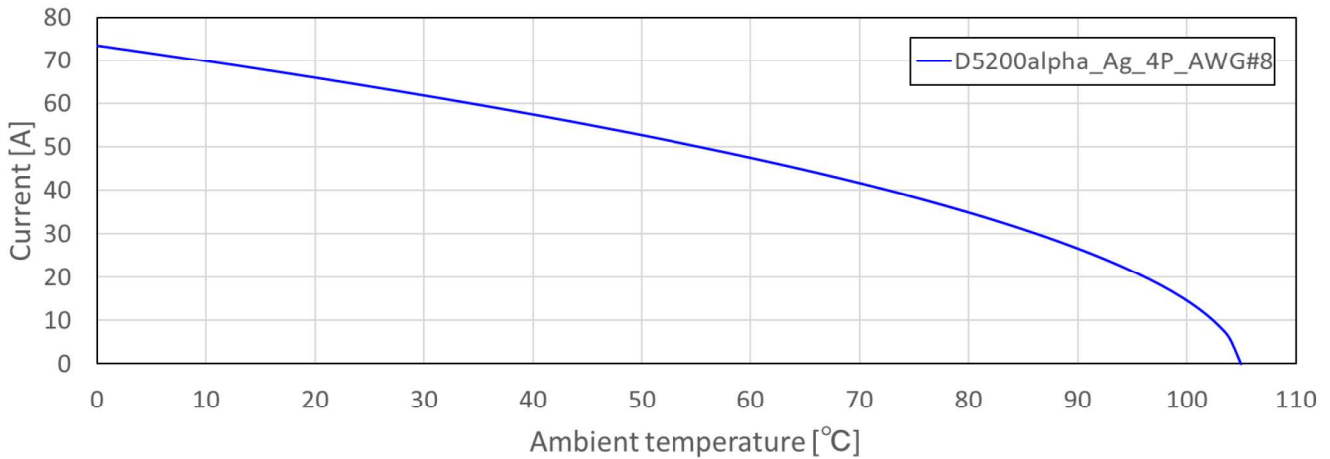


Figure 1



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